

# Product / Process Change Notification



N° 2013-048-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

## Implementation of halogen-free<sup>1)</sup> mold compound and copper wire bonding for products assembled in lead-free package PG-TSOP-6

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before ~~31. December 2013~~ **03. January 2014**.
- Infineon aligns with the widely-recognized JEDEC STANDARD "JESD46", which stipulates: "Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."
- This PCN includes a **Product Discontinuation Notice** (JEDEC STANDARD "JESD48") on page 5-6

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

### Disclaimer:

If we do not receive any response by the date in the PCN above we consider this as the acceptance of the PCN. After the last order date as stated herein, purchase orders related to the unchanged product(s) cannot be accepted.

In case the customer rejects this PCN this PCN shall be considered a product discontinuation notice (PD).

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**SUBJECT OF CHANGE:** Implementation of halogen-free<sup>1)</sup> mold compound and copper wire bonding.

**<sup>1)</sup>Note**

Infineon products defined as halogen-free according to

IEC 61249-2-21 meet the following requirements:

- 900 ppm maximum Chlorine
- 900 ppm maximum Bromine
- 1500 ppm maximum sum of Chlorine and Bromine

All homogeneous materials in the final product defined as halogen-free according to IEC 61249-2-21 meet these voluntary substance thresholds defined by the International Electrotechnical Commission (IEC).

**PRODUCTS AFFECTED:** Products assembled at site Infineon Technologies (Malaysia) Sdn. Bhd. in lead-free package TSOP6 (see 1\_cip13048\_a)

**REASON OF CHANGE:** To adequately react on the increasing customer requests for eco-friendly products.

<b>DESCRIPTION OF CHANGE:</b>	<b><u>OLD</u></b>	<b><u>NEW</u></b>
■ <b>Mold Compound</b>	Halogen containing mold compound	Halogen-free mold compound
■ <b>Wire Bonding Material</b>	Au Wire	Cu Wire
■ <b>Product Barcode Label</b>	Pb free logo	Pb free and halogen-free logo

# Product / Process Change Notification

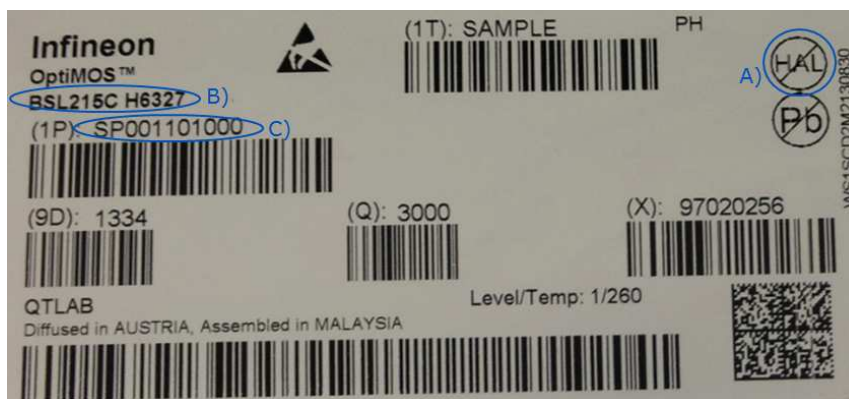


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## PRODUCT IDENTIFICATION:

External traceability

Barcode Product Label (BPL)



- A) Halogen-free logo printed on barcode label
- B) "L" in sales code will be substituted by "H" to indicate the halogen free<sup>1)</sup> mould compound
- C) New customer ordering code

Internal traceability

Ensured via lot number and date code marking

## TIME SCHEDULE:

- Final qualification report: see attachment 2\_cip13048\_a
- First samples available: On request (leadtime up to 8 weeks)
- Start of delivery: from December 2013 onwards for defined products
- Last order date of unchanged product: ~~15-04-2014~~ 03-06-2014 See page 5/6
- Last delivery date of unchanged product: ~~15-11-2014~~ 03-12-2014 See page 5/6

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N° 2013-048-A

## ASSESSMENT:

- Halogen-free according to IEC 61249-2-21
- No change in electrical performance as defined in applied datasheets
- No change in quality and reliability
- Product reliability verified by full product qualification
- Advantages of Cu wire compared to Au wire (see 3\_cip13048\_a)

## DOCUMENTATION:

1\_cip13048\_a

Affected products

2\_cip13048\_a

Final Qualification Report

3\_cip13048\_a

Customer information package:  
Additional information on Cu wiring

# PRODUCT DISCONTINUATION

PD13048



referring to PCN N° 2013-048-A

- Last order date of unchanged product: ~~2014-04-15~~ 2014-06-03
- Last delivery date of unchanged product ~~2014-11-15~~ 2014-12-03

DISCONTINUED				NEW (REPLACEMENT)		
Device	SP N°	OPN	Package	Device	SP N°	Package
BSL202SN L6327	SP000257782	BSL202SNL6327HTSA1	PG-TSOP6-6	BSL202SN H6327	SP001100644	PG-TSOP6-6
BSL205N L6327	SP000442386	BSL205NL6327HTSA1	PG-TSOP6-6	BSL205N H6327	SP001100646	PG-TSOP6-6
BSL207N L6327	SP000442426	BSL207NL6327HTSA1	PG-TSOP6-6	BSL207N H6327	SP001100648	PG-TSOP6-6
BSL207SP L6327	SP000095796	BSL207SPL6327HTSA1	PG-TSOP6-6	BSL207SP H6327	SP001100650	PG-TSOP6-6
BSL211SP L6327	SP000095797	BSL211SPL6327HTSA1	PG-TSOP6-6	BSL211SP H6327	SP001100652	PG-TSOP6-6
BSL214N L6327	SP000442430	BSL214NL6327HTSA1	PG-TSOP6-6	BSL214N H6327	SP001100658	PG-TSOP6-6
BSL215C L6327	SP000442436	BSL215CL6327HTSA1	PG-TSOP6-6	BSL215C H6327	SP001101000	PG-TSOP6-6
BSL302SN L6327	SP000257783	BSL302SNL6327HTSA1	PG-TSOP6-6	BSL302SN H6327	SP001100662	PG-TSOP6-6
BSL306N L6327	SP000442404	BSL306NL6327HTSA1	PG-TSOP6-6	BSL306N H6327	SP001100664	PG-TSOP6-6
BSL307SP L6327	SP000095798	BSL307SPL6327HTSA1	PG-TSOP6-6	BSL307SP H6327	SP001100660	PG-TSOP6-6

# PRODUCT DISCONTINUATION

PD13048



referring to PCN N° 2013-048-A

DISCONTINUED				NEW (REPLACEMENT)		
Device	SP N°	OPN	Package	Device	SP N°	Package
BSL308C L6327	SP000473910	BSL308CL6327HTSA1	PG-TSOP6-6	BSL308C H6327	SP001101002	PG-TSOP6-6
BSL308PE L6327	SP000472978	BSL308PEL6327HTSA1	PG-TSOP6-6	BSL308PE H6327	SP001101004	PG-TSOP6-6
BSL314PE L6327	SP000473004	BSL314PEL6327HTSA1	PG-TSOP6-6	BSL314PE H6327	SP001101006	PG-TSOP6-6
BSL316C L6327	SP000442412	BSL316CL6327HTSA1	PG-TSOP6-6	BSL316C H6327	SP001101010	PG-TSOP6-6
BSL802SN L6327	SP000442478	BSL802SNL6327HTSA1	PG-TSOP6-6	BSL802SN H6327	SP001101012	PG-TSOP6-6
BSL806N L6327	SP000464844	BSL806NL6327HTSA1	PG-TSOP6-6	BSL806N H6327	SP001101014	PG-TSOP6-6

If you have any questions, please do not hesitate to contact your local Sales office.